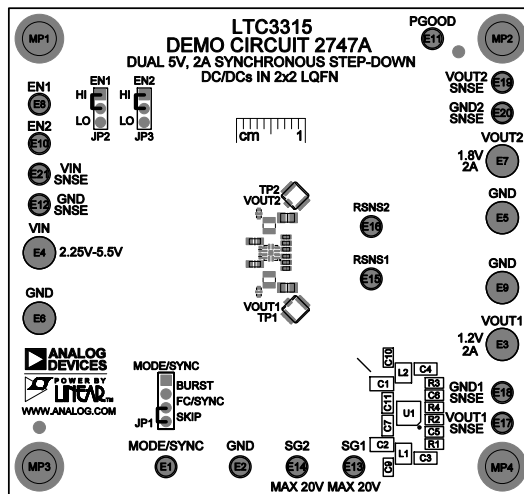


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	04	PRODUCTION	MM	10-07-19

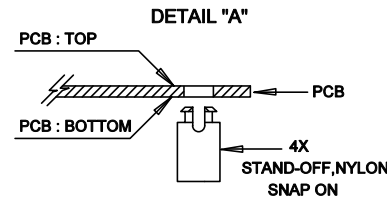
NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY REFLOW PROFILE SHALL BE IN ACCORDANCE WITH J-STD-020 WITH MAXIMUM SOLDER TEMPERATURE OF 250 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
7. INSTALL TURRETS, STAND-OFFS AS SHOWN BELOW:
8. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.

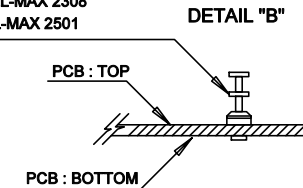




← DETAIL "A"

← DETAIL "B"



(15 PLCS) : MILL-MAX 2308
(6 PLCS) : MILL-MAX 2501



APPROVALS		  FOR ADI CUSTOMER USE ONLY		
PCB DES	NC	TITLE: TOP ASSEMBLY DRAWING DUAL 5V, 2A SYNCHRONOUS STEP-DOWN DC/DCs IN 2x2 LQFN		
APP ENG	MM			
		SIZE	IC NO.	REV.
		N/A	LTC3315A DEMO CIRCUIT 2747A	04
SCALE = NONE		SHT 1 OF 1		